Description

The SX280N10T6 uses advanced technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 100V I_D =280A

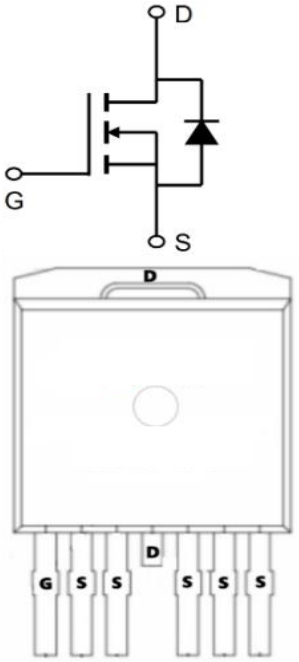
$R_{DS(ON)}$ <2.8mΩ @ V_{GS}=10V

Application

DC/DC Converter

LED Backlighting

Power Management Switches



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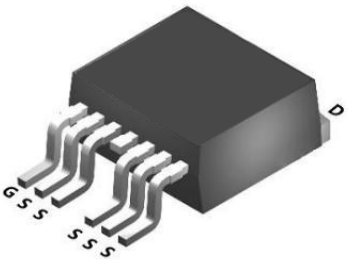


Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	100	V
VGS	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V	280	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V	183	A
IDM	Pulsed Drain Current	900	A
EAS	Single Pulse Avalanche Energy	1028	mJ
IAS	Avalanche Current	54	A
P_D@T_C=25℃	Total Power Dissipation[4]	379	W
TSTG	Storage Temperature Range	-55 to 175	℃
T_J	Operating Junction Temperature Range	-55 to 175	℃
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	0.33	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	60	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	100	107	-	V
IGSS	Gate-body Leakage current	V_{DS}=0V, V_{GS} = ±20V	-	-	±100	nA
IDSS	Zero Gate Voltage Drain Current T_J=25°C	V_{DS}=100V, V_{GS}=0V	-	-	1	μA
IDSS	Zero Gate Voltage Drain Current T_J=100°C		-	-	100	
VGS(th)	Gate-Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	2	3	4	V
RDS(on)	Drain-Source on-Resistance[4]	V_{GS}=10V, I_D=20A	-	2.0	2.8	mΩ
gfs	Forward Transconductance[4]	V_{DS}=10V, I_D=20A	-	76	-	S
Ciss	Input Capacitance	V_{DS}=50V, V_{GS}=0V, f=1MHz	-	9030	-	pF
Coss	Output Capacitance		-	1505	-	
Crss	Reverse Transfer Capacitance		-	40	-	
R_g	Gate Resistance	f =1MHz	-	2.3	-	Ω
Q_g	Total Gate Charge	V_{GS} = 10V, V_{DS} = 50V, I_D=20A	-	150	-	nC
Qgs	Gate-Source Charge		-	32.5	-	
Qgd	Gate-Drain Charge		-	49	-	
td(on)	Turn-on Delay Time	V_{GS} =10V, V_{DD} =50V, R_G = 3Ω, I_D= 20A	-	27	-	ns
t_r	Rise Time		-	78.5	-	
td(off)	Turn-off Delay Time		-	110	-	
t_f	Fall Time		-	86	-	
trr	Body Diode Reverse Recovery Time	I_F = 20A, dI/dt=100A/μs	-	88	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	220	-	nC
VSD	Diode Forward Voltage[4]	I_D = 20A, V_{GS}=0V	-	-	1.2	V
IS	Continuous Source Current T_C=25°C		-	-	220	A

Notes:

1、The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3、The EAS data shows Max. rating . The test condition is V_{DD}=50V, V_{GS}=10V, L=0.5mH, I_{AS}=54A

4、The power dissipation is limited by 150°Cjunction temperature

5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

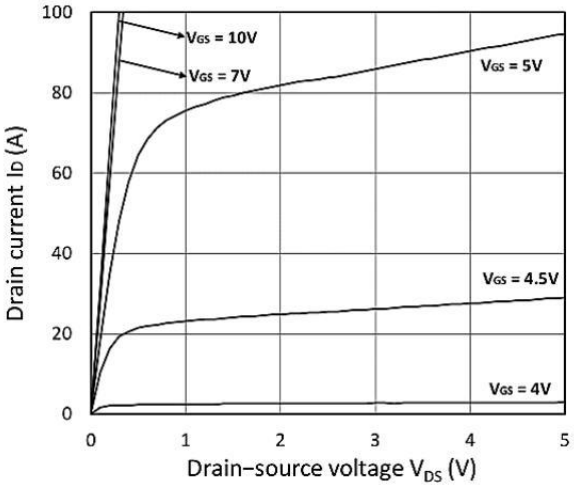


Figure 1. Output Characteristics

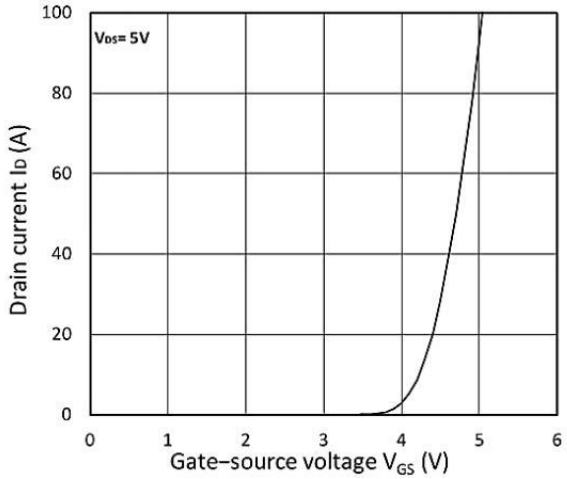


Figure 2. Transfer Characteristics

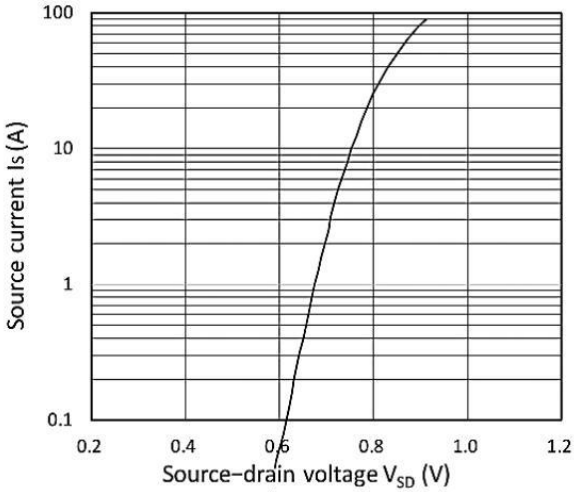


Figure 3. Forward Characteristics of Reverse

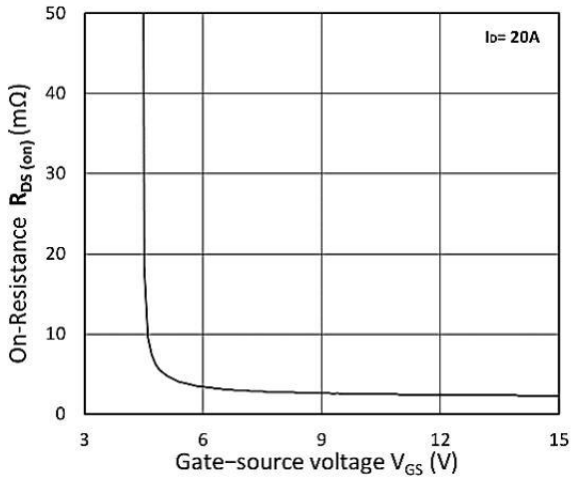


Figure 4. RDS(ON) vs. VGS

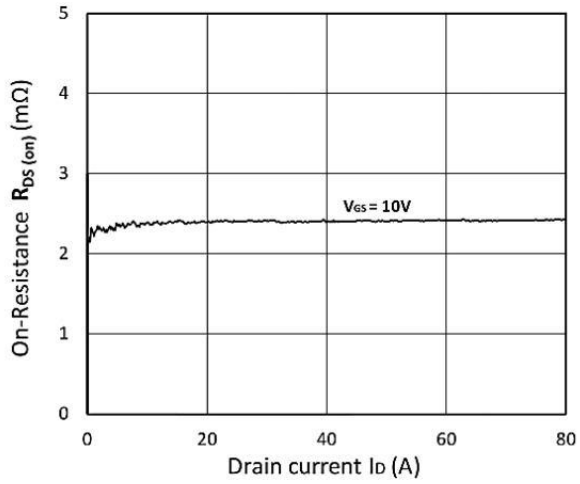


Figure 5. RDS(ON) vs. ID

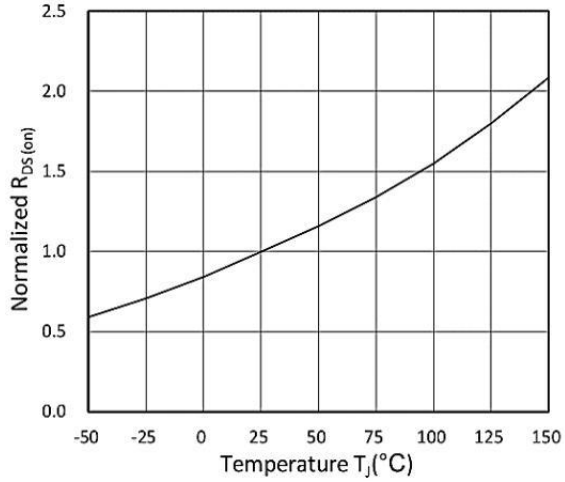


Figure 6. Normalized RDS(on) vs. Temperature

Typical Characteristics

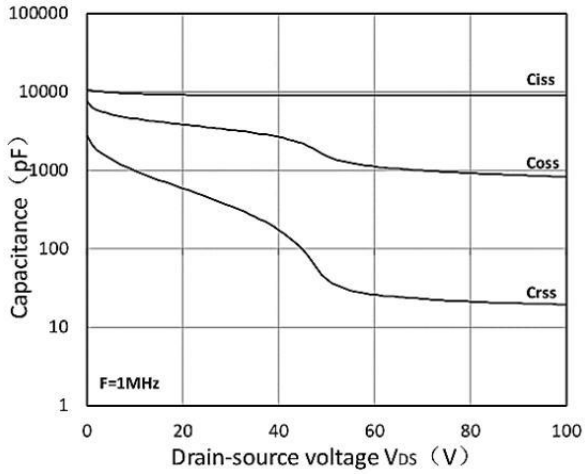


Figure 7. Capacitance Characteristics

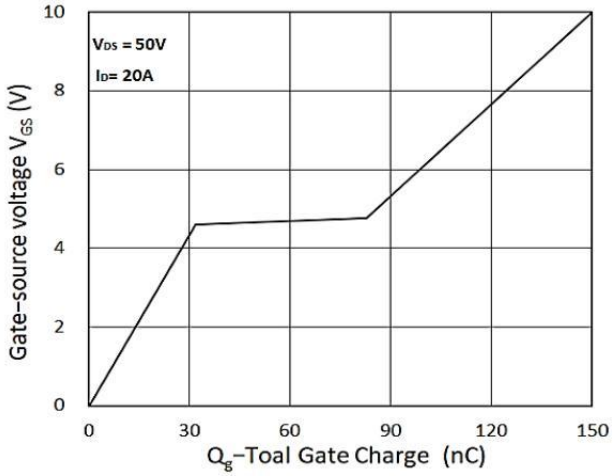


Figure 8. Gate Charge Characteristics

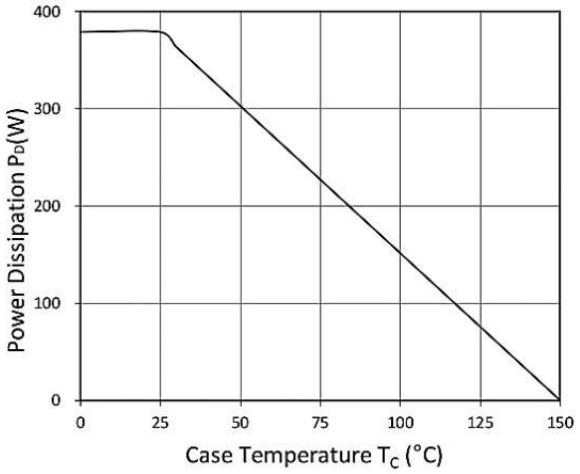


Figure 9. Power Dissipation

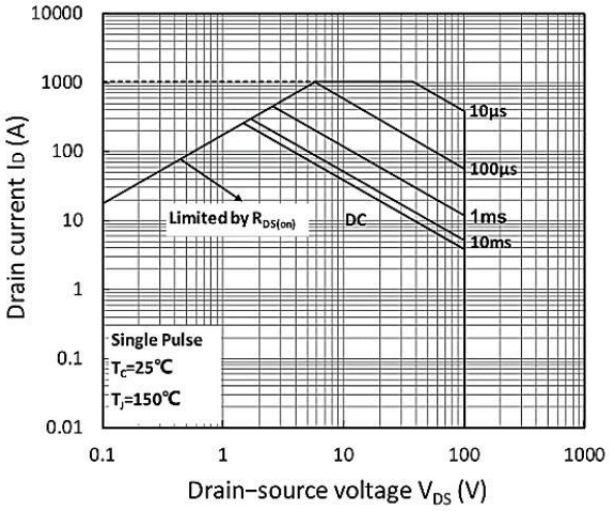


Figure10. Safe Operating Area

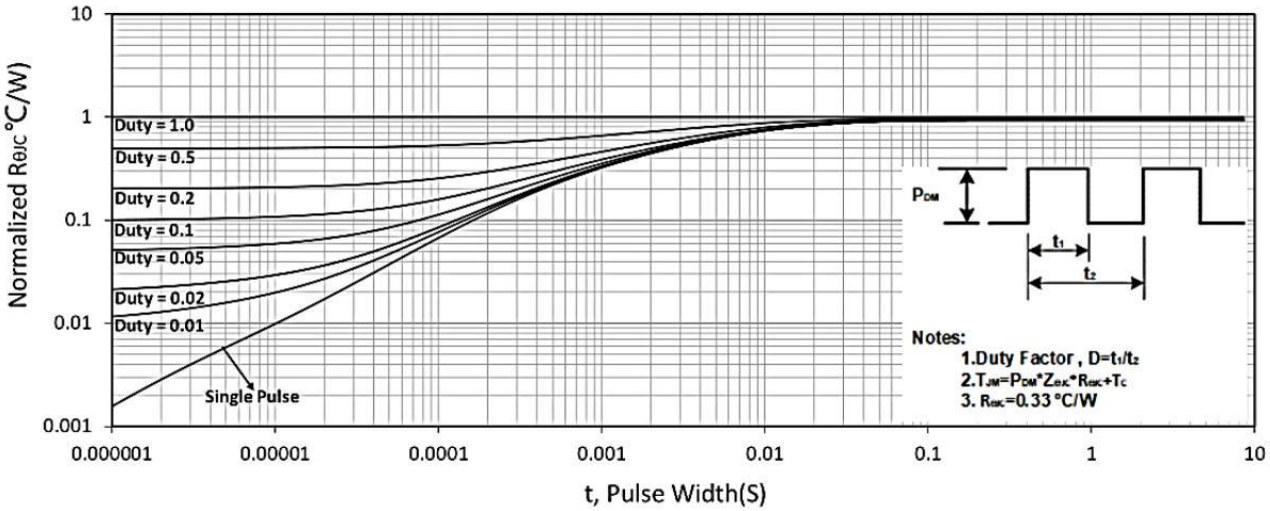
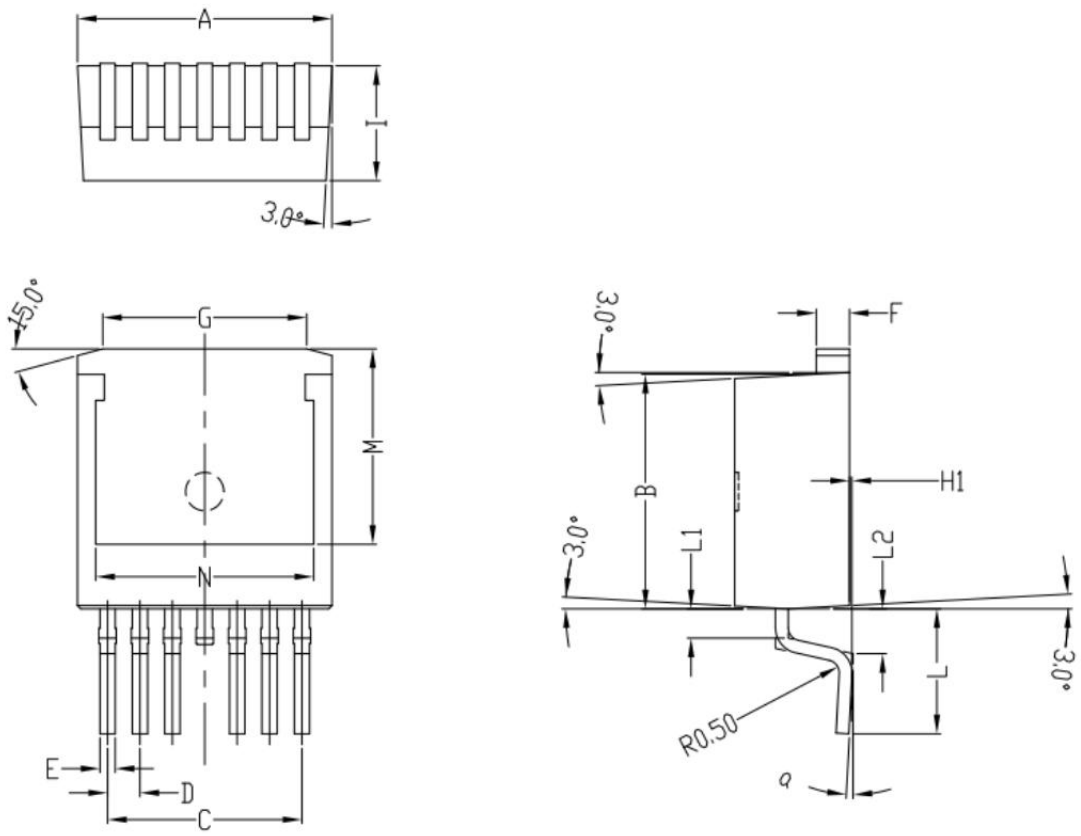


Figure 11. Normalized Maximum Transient Thermal Impedance

Package Mechanical Data-TO263-6L



Symbol	Common		
	mm		
	Mim	Nom	Max
A	9.88	9.98	10.08
B	9.09	9.19	9.29
C	7.54	7.62	7.70
D	1.23	1.27	1.31
E	0.55	0.6	0.65
F	1.27	1.30	1.33
G	7.7	8	8.3
H1	-0.1	+0.10	+0.2
I	4.42	4.50	4.58
L	4.60	4.90	5.20
L1	1.05	1.15	1.25
L2	1.66	1.76	1.86
a	-7°	0°	7°
N	8.25	8.55	8.85
M	7.36	7.66	7.96

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-6L		800